

Title (en)  
ELECTRONICS ASSEMBLY COMPRISING CIRCUIT CARRIER, SEMICONDUCTOR CHIP AND HEAT SINK

Title (de)  
ELEKTRONIK-BAUGRUPPE MIT SCHALTUNGSTRÄGER, HALBLEITERCHIP UND KÜHLKÖRPER

Title (fr)  
MODULE ÉLECTRONIQUE COMPRENANT UN SUPPORT DE CIRCUIT, UNE PUCE SEMI-CONDUCTRICE ET UN DISSIPATEUR THERMIQUE

Publication  
**EP 4302328 A1 20240110 (DE)**

Application  
**EP 22723578 A 20220419**

Priority  
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Abstract (en)  
[origin: WO2022228930A1] An electronics assembly (1) comprising at least one circuit carrier (10a, 10b, 10c), at least one semiconductor chip (20a, 20b) and at least one heat sink (30) is specified, – wherein the electronics assembly (1) has a planar basic shape with a principal plane (P) and is provided in particular for incorporation into a superordinate device, wherein the at least one circuit carrier (10a, 10b, 10c) is oriented parallel to the principal plane (P) and carries one or more semiconductor chips (20a, 20b), to which it is connected in planar fashion, – wherein the at least one heat sink (30) is arranged in a first edge region (RI) of the planar electronics assembly (1), and – wherein the at least one circuit carrier (10a, 10b, 10c) has, between the region of the at least one semiconductor chip (20a, 20b) and the first edge region (RI), at least one thick-film conductor track (11, 13, 16) that is part of a main heat dissipation path (H) running substantially parallel to the principal plane (P). A device comprising such an electronics assembly (1) is furthermore specified.

IPC 8 full level  
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